

DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

(X) Original () Supplemental () Substitute () PCT () DESIGN

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: LEAD FRAME AND PRODUCTION PROCESS THEREOF AND PRODUCTION PROCESS OF THERMALLY CONDUCTIVE SUBSTRATE

of which is described and claimed in:

() the attached specification, or

(X) the specification in application Serial No. _____, filed December 27, 2001, and with amendments through _____, or

() the specification in International Application No. _____, filed _____, and as amended on _____ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose to the Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any application(s) for patent or inventor's certificate listed below and have also identified below any application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	2000-397650	December 27, 2000	YES
Japan	2000-397651	December 27, 2000	YES

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; and Michael S. Huppert, Reg. No. 40,268, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from AOYAMA & PARTNERS, as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

Direct Correspondence to Customer No:



000513

PATENT TRADEMARK OFFICE

Direct Telephone Calls to:

WENDEROTH, LIND & PONACK, L.L.P.
2033 "K" Street, N.W., Suite 800
Washington, D.C. 20006-1021

Phone: (202) 721-8200
Fax: (202) 721-8250

Full Name of First Inventor	FAMILY NAME YAMASHITA		FIRST GIVEN NAME Yoshihisa	SECOND GIVEN NAME
	CITY Kyoto-shi		STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Residence & Citizenship	ADDRESS 2-4-618, Mibubojo, 48-3, Mibubojocho, Nakagyo-ku, Kyoto-shi, Kyoto-fu,		CITY	STATE OR COUNTRY
	Address		ZIP CODE	

Full Name of Second Inventor	FAMILY NAME HIRANO		FIRST GIVEN NAME Koichi	SECOND GIVEN NAME
	CITY Hirakata-shi		STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Residence & Citizenship	ADDRESS 2-9-15-612, Makinosaka, Hirakata-shi, Osaka-fu, Japan		CITY	STATE OR COUNTRY
	Address		ZIP CODE	

Full Name of Third Inventor	FAMILY NAME NAKATANI		FIRST GIVEN NAME Seiichi	SECOND GIVEN NAME
	CITY Hirakata-shi		STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Residence & Citizenship	ADDRESS 11-29-16, Korigaoka, Hirakata-shi, Osaka-fu, Japan		CITY	STATE OR COUNTRY
	Address		ZIP CODE	

Full Name of Fourth Inventor	FAMILY NAME SUZUMURA		FIRST GIVEN NAME Masaki	SECOND GIVEN NAME
	CITY Hisai-shi		STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Residence & Citizenship	ADDRESS 163-2, Ibacho, Hisai-shi, Mie-ken, Japan		CITY	STATE OR COUNTRY
	Address		ZIP CODE	

Full Name of Fifth Inventor	FAMILY NAME		FIRST GIVEN NAME	SECOND GIVEN NAME
	CITY		STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
Residence & Citizenship	ADDRESS		CITY	STATE OR COUNTRY
	Address		ZIP CODE	

Full Name of Sixth Inventor	FAMILY NAME		FIRST GIVEN NAME	SECOND GIVEN NAME
	CITY		STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
Residence & Citizenship	ADDRESS		CITY	STATE OR COUNTRY
	Address		ZIP CODE	

Post Office Address	ADDRESS	CITY	STATE OR COUNTRY	ZIP CODE
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I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor _____ Date _____
Yoshihisa YAMASHITA
2nd Inventor _____ Date _____
Koichi HIRANO
3rd Inventor _____ Date _____
Seichi NAKATANI
4th Inventor _____ Date _____
Masaki SUZUMURA
5th Inventor _____ Date _____
6th Inventor _____ Date _____

The above application may be more particularly identified as follows:

U.S. Application Serial No. _____ Filing Date December 27, 2001

Applicant Reference Number 534642 Atty Docket No. 2001_1854A

Title of Invention LEAD FRAME AND PRODUCTION PROCESS THEREOF AND PRODUCTION PROCESS OF THERMALLY CONDUCTIVE SUBSTRATE